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March 2015

### FDD8780/FDU8780

## N-Channel PowerTrench® MOSFET

**25V**, **35A**, **8.5m**Ω

#### **General Description**

This N-Channel MOSFET has been designed specifically to improve the overall efficiency of DC/DC converters using either synchronous or conventional switching PWM controllers. It has been optimized for low gate charge, low  $r_{\text{DS}(\text{on})}$  and fast switching speed.

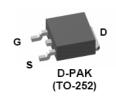
#### **Application**

- Vcore DC-DC for Desktop Computers and Servers
- VRM for Intermediate Bus Architecture

#### **Features**

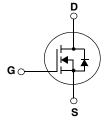
- Max  $r_{DS(on)}$  = 8.5m $\Omega$  at  $V_{GS}$  = 10V,  $I_D$  = 35A
- Max  $r_{DS(on)}$  = 12.0m $\Omega$  at  $V_{GS}$  = 4.5V,  $I_D$  = 35A
- Low gate charge:  $Q_{g(10)} = 21nC(Typ)$ ,  $V_{GS} = 10V$
- Low gate resistance
- Avalanche rated and 100% tested
- RoHS Compliant











#### MOSFET Maximum Ratings T<sub>C</sub> = 25°C unless otherwise noted

Symbol	Parameter		Ratings	Units
$V_{DS}$	Drain to Source Voltage		25	V
$V_{GS}$	Gate to Source Voltage		±20	V
I <sub>D</sub>	Drain Current -Continuous (Package Limited)		35	
	-Continuous (Die Limited)		60	Α
	-Pulsed	(Note 1)	224	
E <sub>AS</sub>	Single Pulse Avalanche Energy	(Note 2)	73	mJ
$P_{D}$	Power Dissipation		50	W
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Temperature		-55 to 175	°C

#### **Thermal Characteristics**

$R_{\thetaJC}$	Thermal Resistance, Junction to Case TO-252,TO-251	3.0	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient TO-252,TO-251	100	°C/W
R <sub>e,IA</sub>	Thermal Resistance, Junction to Ambient TO-252,1in <sup>2</sup> copper pad area	52	°C/W

#### **Package Marking and Ordering Information**

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDD8780	FDD8780	TO-252AA	13"	16mm	2500 units
FDU8780	FDU8780	TO-251AA	N/A(Tube)	N/A	75 units
FDU8780	FDU8780_F071	TO-251AA	N/A(Tube)	N/A	75 units

Electrical	Charac	teristics	$T_{\rm J} = 25^{\circ}$	C unless otherwise noted
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Symbol	Parameter	Test Conditions	Min	Тур	Max	Units			
Off Characteristics									
B <sub>VDSS</sub>	Drain to Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V$	25			V			
$\frac{\Delta B_{VDSS}}{\Delta T_{J}}$	Breakdown Voltage Temperature Coefficient	$I_D$ = 250 $\mu$ A, referenced to 25°C		12		mV/°C			
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 20V, V <sub>GS</sub> = 0V			1 250	μА			
I <sub>GSS</sub>	Gate to Source Leakage Current	$V_{GS} = \pm 20V$			±100	nA			

#### **On Characteristics**

V <sub>GS(th)</sub>	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = 250 \mu A$	1.2	1.8	2.5	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate to Source Threshold Voltage Temperature Coefficient	$I_D$ = 250 $\mu$ A, referenced to 25°C		-6.3		mV/°C
	Drain to Source On Resistance	V <sub>GS</sub> = 10V, I <sub>D</sub> = 35A		6.5	8.5	
rpo()		V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 35A		9.1	12.0	mΩ
r <sub>DS(on)</sub>		$V_{GS}$ = 10V, $I_D$ = 35A $T_J$ = 175°C		10.4	15.0	11152

#### **Dynamic Characteristics**

C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> = 13V, V <sub>GS</sub> = 0V, f = 1MHz	1080	1440	pF
Coss	Output Capacitance		265	355	pF
C <sub>rss</sub>	Reverse Transfer Capacitance		180	270	pF
$R_g$	Gate Resistance	f = 1MHz	0.9		Ω

#### **Switching Characteristics**

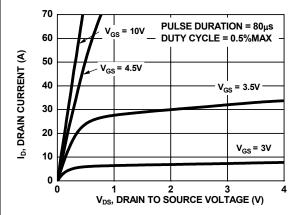
t <sub>d(on)</sub>	Turn-On Delay Time		7	14	ns
t <sub>r</sub>	Rise Time	$V_{DD}$ = 13V, $I_{D}$ = 35A $V_{GS}$ = 10V, $R_{GS}$ = 17 $\Omega$	9	18	ns
t <sub>d(off)</sub>	Turn-Off Delay Time	$V_{GS} = 10V, R_{GS} = 1722$	43	69	ns
t <sub>f</sub>	Fall Time		24	38	ns
Qg	Total Gate Charge	V <sub>GS</sub> = 0V to 10V	21	29	nC
Qg	Total Gate Charge	$V_{GS} = 0V \text{ to } 5V$ $V_{DD} = 13V$ $I_{D} = 35A$	11.2	16	nC
Q <sub>gs</sub>	Gate to Source Gate Charge	$I_D = 35A$ $I_C = 1.0 \text{mA}$	3.5		nC
$Q_{gd}$	Gate to Drain "Miller" Charge	.g	4.7		nC

#### **Drain-Source Diode Characteristics**

V	V		V <sub>GS</sub> = 0V, I <sub>S</sub> = 35A	0.92	1.25	V
	v <sub>SD</sub>		V <sub>GS</sub> = 0V, I <sub>S</sub> = 15A	0.84	1.0	v
	t <sub>rr</sub>	Reverse Recovery Time	$I_F = 35A$ , di/dt = 100A/ $\mu$ s	28	42	ns
	Q <sub>rr</sub>	Reverse Recovery Charge	$I_F = 35A$ , di/dt = $100A/\mu s$	20	30	nC

Notes:
1: Pulse time < 300μs, Duty cycle = 2%.
2: Starting T<sub>J</sub> = 25°C, L = 0.3mH, I<sub>AS</sub> = 22A ,V<sub>DD</sub> = 23V, V<sub>GS</sub> = 10V.





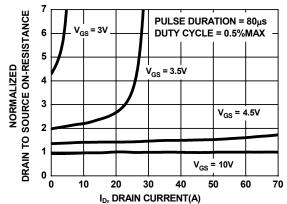
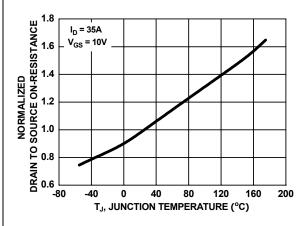


Figure 1. On Region Characteristics

Figure 2. Normalized On-Resistance vs Drain Current and Gate Voltage



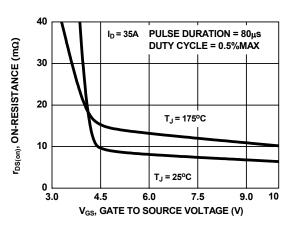
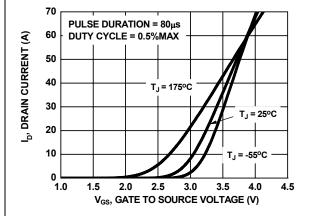


Figure 3. Normalized On Resistance vs Junction Temperature

Figure 4. On-Resistance vs Gate to Source Voltage



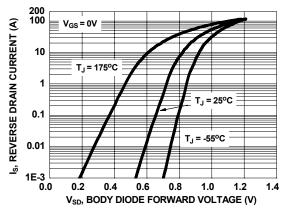
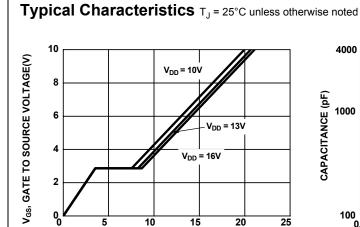


Figure 5. Transfer Characteristics

Figure 6. Source to Drain Diode Forward Voltage vs Source Current



4000

(Lg)
1000

(Ciss

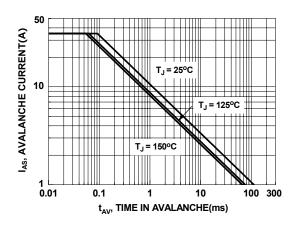
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Figure 7. Gate Charge Characteristics

Qq, GATE CHARGE(nC)

Figure 8. Capacitance vs Drain to Source Voltage



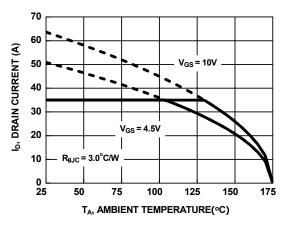
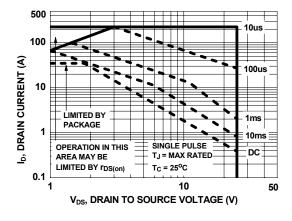


Figure 9. Unclamped Inductive Switching Capability

Figure 10. Maximum Continuous Drain Current vs Case Temperature



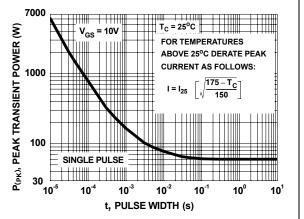


Figure 11. Forward Bias Safe Operating Area

Figure 12. Single Pulse Maximum Power Dissipation

10<sup>1</sup>

10°

10<sup>-1</sup>

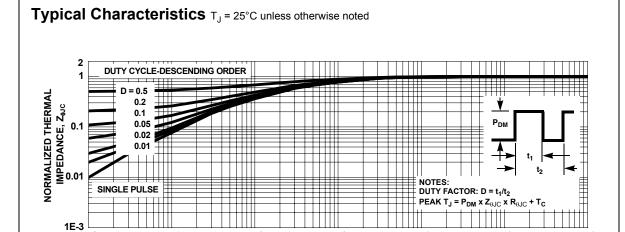


Figure 13. Transient Thermal Response Curve

10<sup>3</sup> 10<sup>2</sup> t, RECTANGULAR PULSE DURATION(s)

10<sup>-4</sup>

10<sup>-5</sup>



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